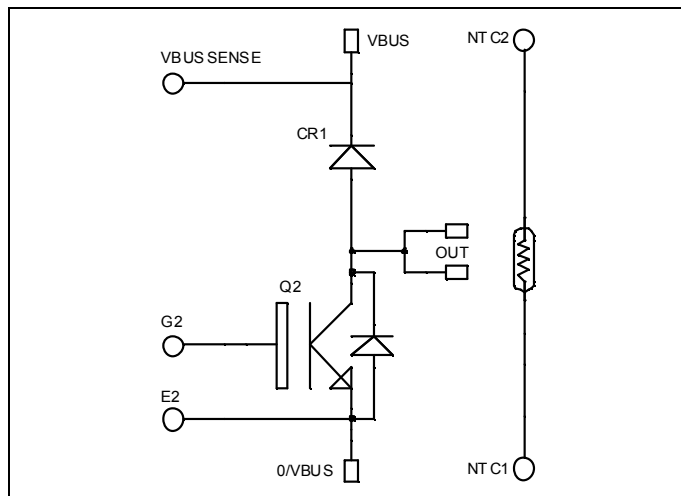


## Boost chopper Trench + Field Stop IGBT® Power Module

**$V_{CES} = 1700V$**   
 **$I_C = 100A @ T_c = 80^\circ C$**

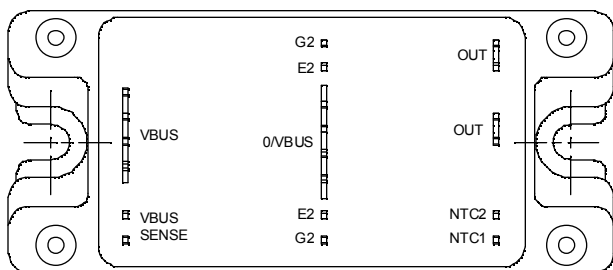


### Application

- AC and DC motor control
- Switched Mode Power Supplies
- Power Factor Correction

### Features

- Trench + Field Stop IGBT® Technology
  - Low voltage drop
  - Low tail current
  - Switching frequency up to 20 kHz
  - Soft recovery parallel diodes
  - Low diode VF
  - Low leakage current
  - Avalanche energy rated
  - RBSOA and SCSOA rated
- Kelvin emitter for easy drive
- Very low stray inductance
  - Symmetrical design
  - Lead frames for power connections
- High level of integration
- Internal thermistor for temperature monitoring



### Benefits

- Stable temperature behavior
- Very rugged
- Solderable terminals for easy PCB mounting
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Easy paralleling due to positive TC of VCEsat
- Low profile
- RoHS Compliant

### Absolute maximum ratings

| Symbol    | Parameter                             | Max ratings                              | Unit                                          |
|-----------|---------------------------------------|------------------------------------------|-----------------------------------------------|
| $V_{CES}$ | Collector - Emitter Breakdown Voltage | 1700                                     | V                                             |
| $I_C$     | Continuous Collector Current          | $T_c = 25^\circ C$<br>$T_c = 80^\circ C$ | $\begin{matrix} 150 \\ 100 \end{matrix}$<br>A |
| $I_{CM}$  | Pulsed Collector Current              | $T_c = 25^\circ C$                       | 200                                           |
| $V_{GE}$  | Gate - Emitter Voltage                | $\pm 20$                                 | V                                             |
| $P_D$     | Maximum Power Dissipation             | $T_c = 25^\circ C$                       | 560                                           |
| RBSOA     | Reverse Bias Safe Operating Area      | $T_j = 125^\circ C$                      | 200A @ 1600V                                  |

**CAUTION:** These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on [www.microsemi.com](http://www.microsemi.com)

All ratings @  $T_j = 25^\circ\text{C}$  unless otherwise specified

**Electrical Characteristics**

| Symbol        | Characteristic                       | Test Conditions                                | Min                                                   | Typ        | Max | Unit          |
|---------------|--------------------------------------|------------------------------------------------|-------------------------------------------------------|------------|-----|---------------|
| $I_{CES}$     | Zero Gate Voltage Collector Current  | $V_{GE} = 0\text{V}$ , $V_{CE} = 1700\text{V}$ |                                                       |            | 250 | $\mu\text{A}$ |
| $V_{CE(sat)}$ | Collector Emitter Saturation Voltage | $V_{GE} = 15\text{V}$<br>$I_C = 100\text{A}$   | $T_j = 25^\circ\text{C}$<br>$T_j = 125^\circ\text{C}$ | 2.0<br>2.4 | 2.4 | V             |
| $V_{GE(th)}$  | Gate Threshold Voltage               | $V_{GE} = V_{CE}$ , $I_C = 2\text{mA}$         | 5.0                                                   | 5.8        | 6.5 | V             |
| $I_{GES}$     | Gate – Emitter Leakage Current       | $V_{GE} = 20\text{V}$ , $V_{CE} = 0\text{V}$   |                                                       |            | 400 | nA            |

**Dynamic Characteristics**

| Symbol       | Characteristic               | Test Conditions                                  | Min                       | Typ  | Max | Unit |
|--------------|------------------------------|--------------------------------------------------|---------------------------|------|-----|------|
| $C_{ies}$    | Input Capacitance            | $V_{GE} = 0\text{V}$                             |                           | 9    |     | nF   |
| $C_{oes}$    | Output Capacitance           | $V_{CE} = 25\text{V}$                            |                           | 0.36 |     |      |
| $C_{res}$    | Reverse Transfer Capacitance | $f = 1\text{MHz}$                                |                           | 0.3  |     |      |
| $T_{d(on)}$  | Turn-on Delay Time           | Inductive Switching ( $25^\circ\text{C}$ )       |                           | 370  |     | ns   |
| $T_r$        | Rise Time                    | $V_{GE} = 15\text{V}$                            |                           | 40   |     |      |
| $T_{d(off)}$ | Turn-off Delay Time          | $V_{Bus} = 900\text{V}$                          |                           | 650  |     |      |
| $T_f$        | Fall Time                    | $I_C = 100\text{A}$<br>$R_G = 4.7\ \Omega$       |                           | 180  |     |      |
| $T_{d(on)}$  | Turn-on Delay Time           | Inductive Switching ( $125^\circ\text{C}$ )      |                           | 400  |     | ns   |
| $T_r$        | Rise Time                    | $V_{GE} = 15\text{V}$                            |                           | 50   |     |      |
| $T_{d(off)}$ | Turn-off Delay Time          | $V_{Bus} = 900\text{V}$                          |                           | 800  |     |      |
| $T_f$        | Fall Time                    | $I_C = 100\text{A}$<br>$R_G = 4.7\ \Omega$       |                           | 300  |     |      |
| $E_{on}$     | Turn-on Switching Energy     | $V_{GE} = 15\text{V}$<br>$V_{Bus} = 900\text{V}$ | $T_j = 125^\circ\text{C}$ | 32   |     | mJ   |
| $E_{off}$    | Turn-off Switching Energy    | $I_C = 100\text{A}$<br>$R_G = 4.7\ \Omega$       | $T_j = 125^\circ\text{C}$ | 31   |     |      |

**Chopper diode ratings and characteristics**

| Symbol    | Characteristic                          | Test Conditions                                                                  | Min                                                   | Typ        | Max        | Unit          |
|-----------|-----------------------------------------|----------------------------------------------------------------------------------|-------------------------------------------------------|------------|------------|---------------|
| $V_{RRM}$ | Maximum Peak Repetitive Reverse Voltage |                                                                                  | 1700                                                  |            |            | V             |
| $I_{RM}$  | Maximum Reverse Leakage Current         | $V_R = 1700\text{V}$                                                             | $T_j = 25^\circ\text{C}$<br>$T_j = 125^\circ\text{C}$ |            | 250<br>500 | $\mu\text{A}$ |
| $I_F$     | DC Forward Current                      |                                                                                  | $T_c = 80^\circ\text{C}$                              | 100        |            | A             |
| $V_F$     | Diode Forward Voltage                   | $I_F = 100\text{A}$                                                              | $T_j = 25^\circ\text{C}$<br>$T_j = 125^\circ\text{C}$ | 1.8<br>1.9 | 2.2        | V             |
| $t_{rr}$  | Reverse Recovery Time                   | $I_F = 100\text{A}$<br>$V_R = 900\text{V}$<br>$di/dt = 1000\text{A}/\mu\text{s}$ | $T_j = 25^\circ\text{C}$                              | 385        |            | ns            |
|           |                                         |                                                                                  | $T_j = 125^\circ\text{C}$                             | 490        |            |               |
| $Q_{rr}$  | Reverse Recovery Charge                 |                                                                                  | $T_j = 25^\circ\text{C}$                              | 25         |            | $\mu\text{C}$ |
|           |                                         |                                                                                  | $T_j = 125^\circ\text{C}$                             | 42         |            |               |
| $E_r$     | Reverse Recovery Energy                 |                                                                                  | $T_j = 25^\circ\text{C}$<br>$T_j = 125^\circ\text{C}$ | 11<br>21   |            | mJ            |

**Temperature sensor NTC** (see application note APT0406 on [www.microsemi.com](http://www.microsemi.com) for more information).

**Symbol Characteristic**

**Min Typ Max Unit**

|             |                     |  |      |  |    |
|-------------|---------------------|--|------|--|----|
| $R_{25}$    | Resistance @ 25°C   |  | 50   |  | kΩ |
| $B_{25/85}$ | $T_{25} = 298.15$ K |  | 3952 |  | K  |

$$R_T = \frac{R_{25}}{\exp \left[ B_{25/85} \left( \frac{1}{T_{25}} - \frac{1}{T} \right) \right]}$$

T: Thermistor temperature  
 $R_T$ : Thermistor value at T

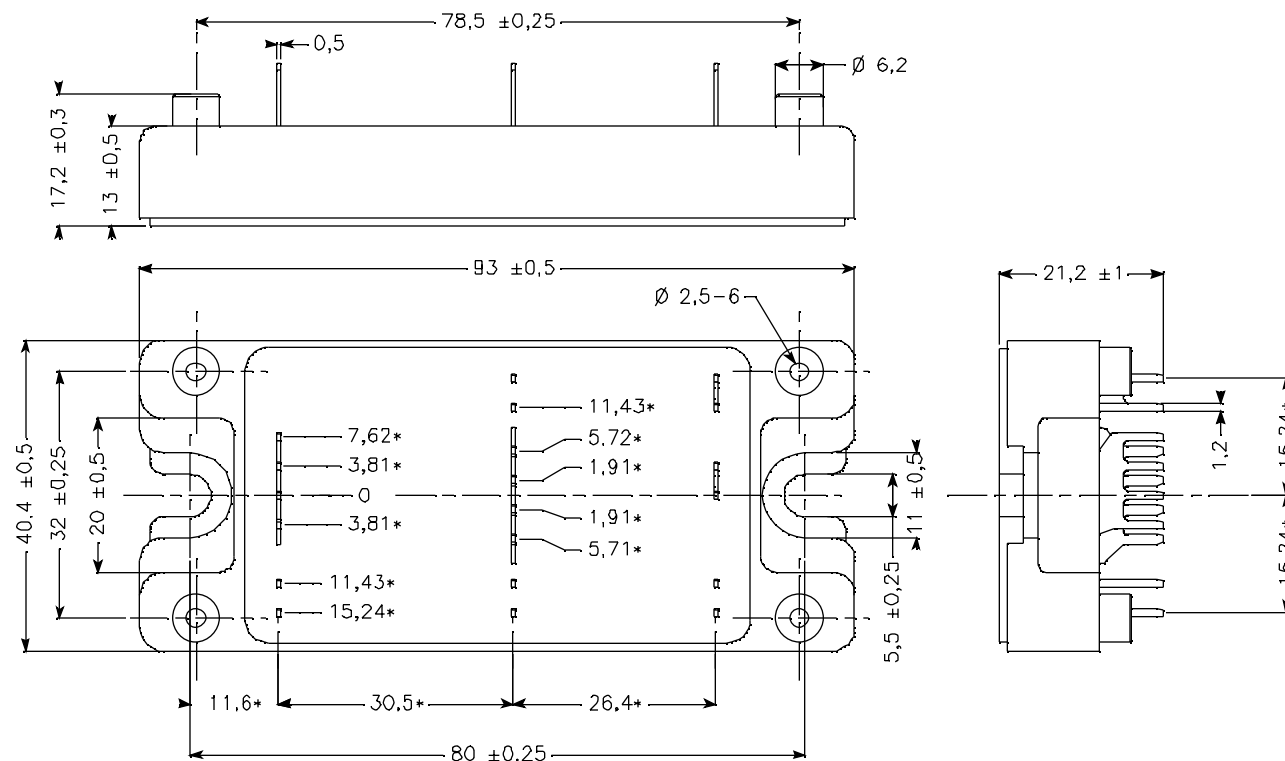
## Thermal and package characteristics

**Symbol Characteristic**

**Min Typ Max Unit**

|            |                                                                          |             |      |     |      |      |
|------------|--------------------------------------------------------------------------|-------------|------|-----|------|------|
| $R_{thJC}$ | Junction to Case Thermal Resistance                                      | IGBT        |      |     | 0.22 | °C/W |
|            |                                                                          | Diode       |      |     | 0.39 |      |
| $V_{ISOL}$ | RMS Isolation Voltage, any terminal to case t=1 min, I isol<1mA, 50/60Hz |             | 3500 |     |      | V    |
| $T_J$      | Operating junction temperature range                                     |             | -40  |     | 150  | °C   |
| $T_{STG}$  | Storage Temperature Range                                                |             | -40  |     | 125  |      |
| $T_C$      | Operating Case Temperature                                               |             | -40  |     | 100  |      |
| Torque     | Mounting torque                                                          | To Heatsink | M5   | 2.5 | 4.7  | N.m  |
| Wt         | Package Weight                                                           |             |      |     | 160  | g    |

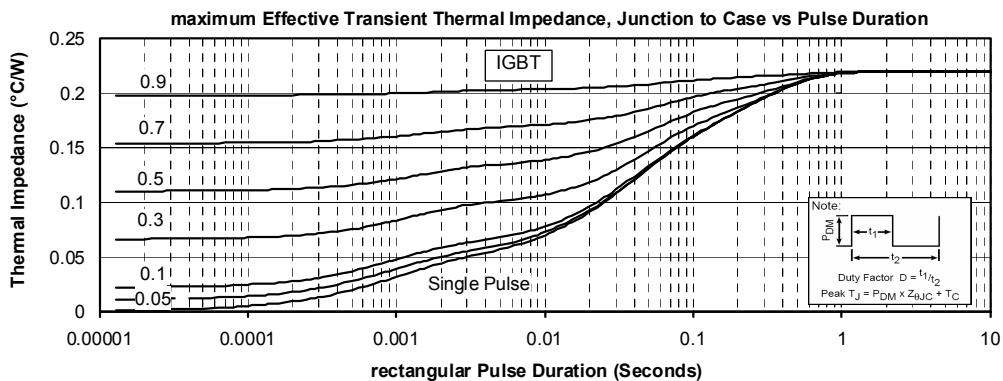
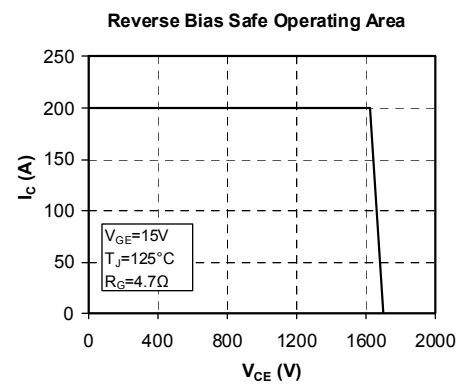
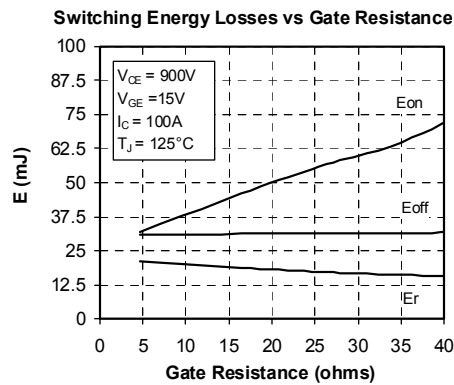
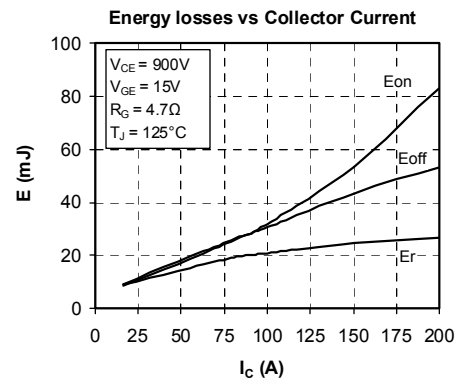
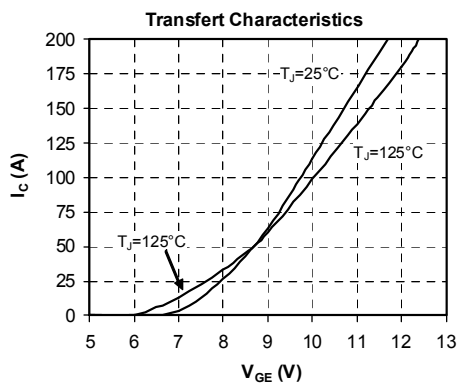
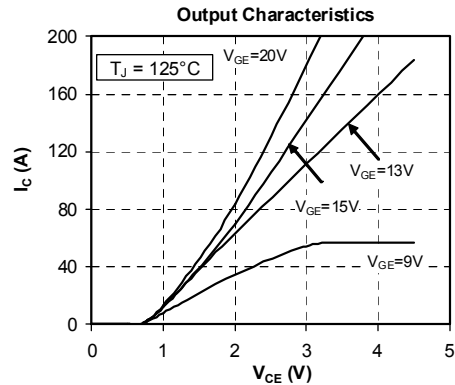
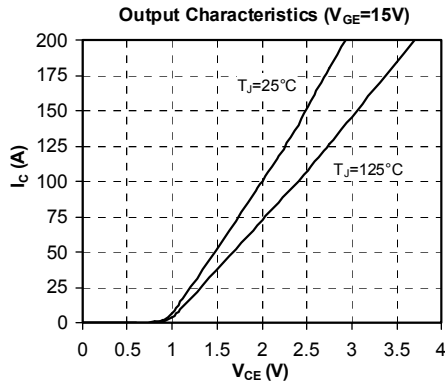
## SP4 Package outline (dimensions in mm)

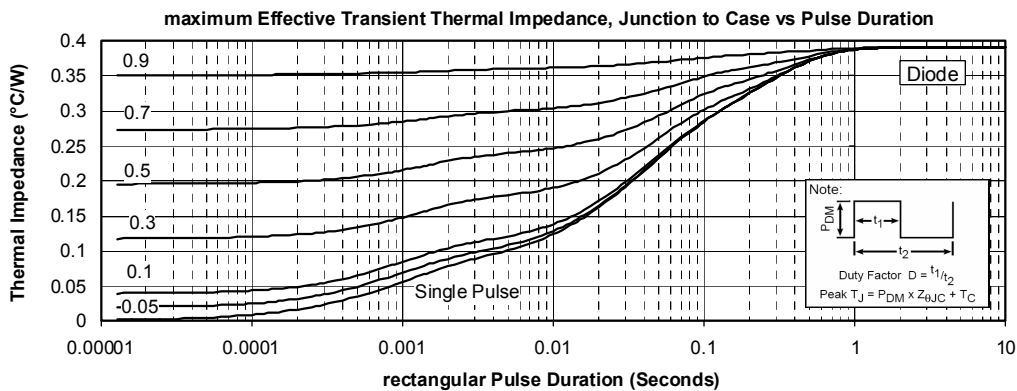
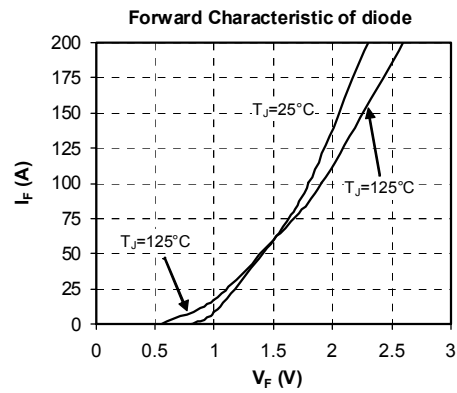
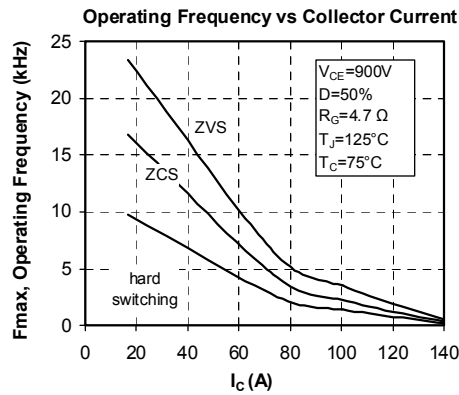


ALL DIMENSIONS MARKED "\*" ARE TOLERENCED AS:  $\pm 0.1$

See application note APT0501 - Mounting Instructions for SP4 Power Modules on [www.microsemi.com](http://www.microsemi.com)

## Typical Performance Curve





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